

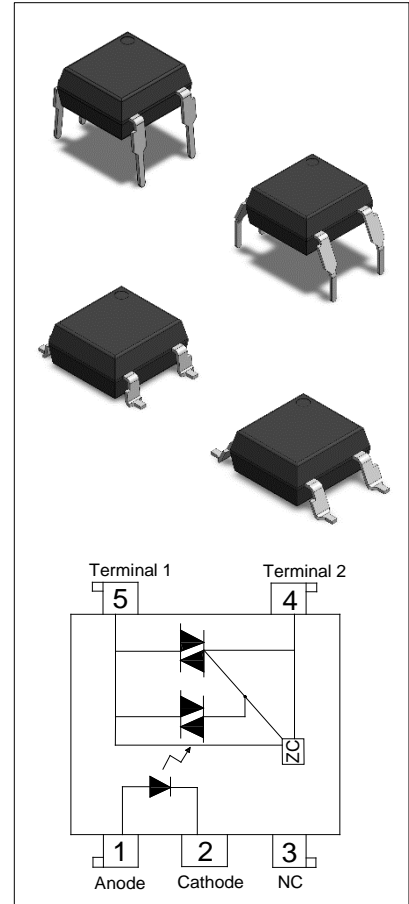


## H11GXF Series

Rev.A.1.0

### DESCRIPTION:

The H11GXF series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo triac to drive a power triac in a plastic DIP5 package with different lead forming options. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors to 265 V<sub>AC</sub> peripherals.



### MAIN FEATURES:

- High isolation 5000 Vrms
- DC input with triac output
- Operating temperature range - 40°C to 85 °C
- REACH & RoHS compliance
- MSL class 2
- HBM: H3A; MM: M4
- CQC approved
- VDE approved
- UL approved

### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit	
Input	Forward Current	$I_F$	60	mA	
	Peak Forward Current	$I_{FP}$	1 <sup>①</sup>	A	
	Reverse Voltage	$V_R$	6	V	
Output	Repetitive peak off-state voltage	$V_{DRM}$	600	V	
	Repetitive peak off-state voltage	$V_{RRM}$	600	V	
	On-state RMS Current	H11G0F	$I_{T(RMS)}$	0.3	A
		H11G1F		0.6	
		H11G2F		0.9	
	Non repetitive surge peak on-state current (full cycle , $t_p=20ms$ )	H11G0F	$I_{TSM}$	3	A
		H11G1F		6	
H11G2F		9			

Isolation Voltage	$V_{iso}$	5000 <sup>②</sup>	Vrms
Operating Temperature	$T_{opr}$	-40~85	°C
Storage Temperature	$T_{stg}$	-40~125	°C
Soldering Temperature	$T_{sol}$	260 <sup>③</sup>	°C

**NOTE1** : 100μs pulse, 100Hz frequency

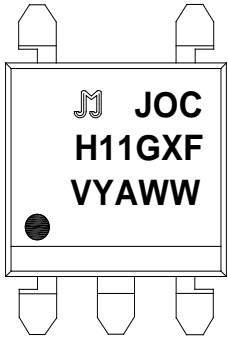
**NOTE2** : AC for 1 minute, R.H.=40~60%

**NOTE3** : For 10 seconds

### ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	$V_F$	$I_F=20mA$	-	1.25	1.4	V
	Reverse Current	$I_R$	$V_R=6V$	-	-	1	μA
Output	Peak Off-state Current, Either Direction	$I_{DRM}$	$V_{DRM}/V_{RRM}=600V, I_F=0$	-	-	10	μA
		$I_{RRM}$		-	-	10	
	Peak On-state Voltage, Either Direction	$V_{TM}$	$I_{TM}=I_{TM} \text{ Rated}$	-	-	2	V
	Critical Rate of Rise of Off-state voltage	dV/dt	$V_D=400V, \text{ Gate Open } I_F=0, T_j=85^\circ C$	1000	-	-	V/μs
Transfer Characteristics	LED Trigger Current	$I_{FT}$	Terminal Voltage=6V $R_L=100\Omega$	-	-	10	mA
	Holding Current	$I_H$	$V_D=6V$	-	-	25	mA
	Isolation Resistance	$R_{ISO}$	DC500V 40~60%R.H.	$10^{12}$	$10^{14}$	-	Ω
	Response Time	$t_{on}$	$V_D=6V, R_L=100\Omega, I_F=20mA$	-	20	100	μs
Zero Crossing	Inhibit Voltage	$V_{IH}$	$I_F=10mA$	-	-	20	V
	Leakage in Inhibit State	$I_{OFF2}$	$I_F=10mA, V_{OFF}=600V$	-	-	500	μA

**ORDERING AND MARKING INFORMATION**

<b>MARKING INFORMATION</b>			
		<p>JOC : Company Abbr.                      H11GXF : Part Number &amp; Rank                      V : VDE Option                      Y : Fiscal Year                      A : Manufacturing Code                      WW : Work Week</p>	
<b>ORDERING INFORMATION</b>			
<b>H11GXF(Y)(Z)-GV</b>			
<p>H11GXF – Part Number &amp; Rank (X=0/1/2)                      Y – Lead Form Option (None/M/SL/SLM)                      Z – Tape and Reel Option (T1/T2)                      G – Green Option (G or None)                      V – VDE Option (V or None)</p>			
<b>Packing Quantity</b>			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
None/M	65 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box =20.8k Units
SL(T1/T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box =15k Units
SLM(T1/T2)	1000 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =10k Units

Characteristics Curves

FIG.1: Forward Current vs. Ambient Temperature

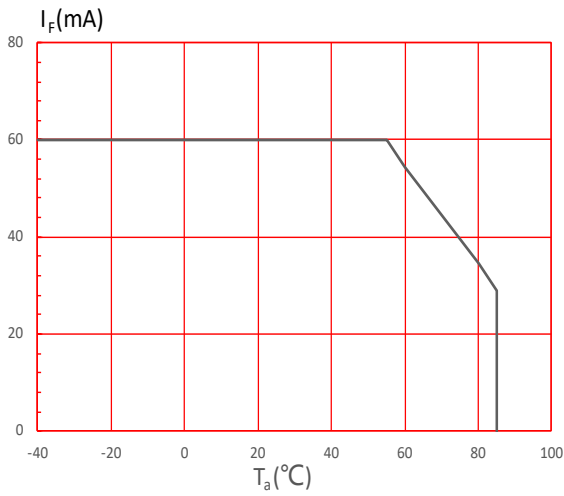


FIG.2: On-state Terminal Current vs. Ambient Temperature

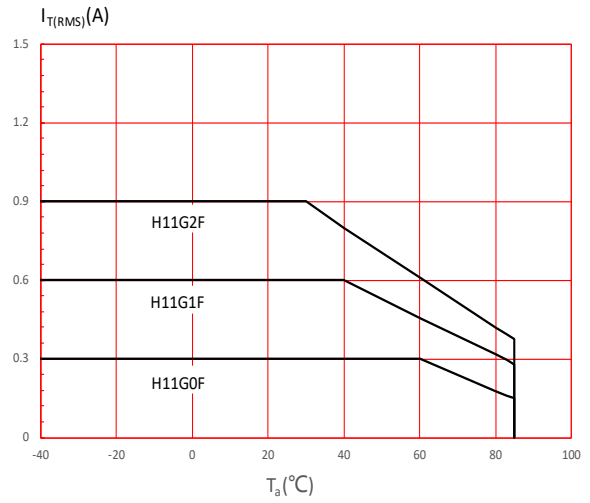


FIG.3: Forward Current vs. Forward Voltage

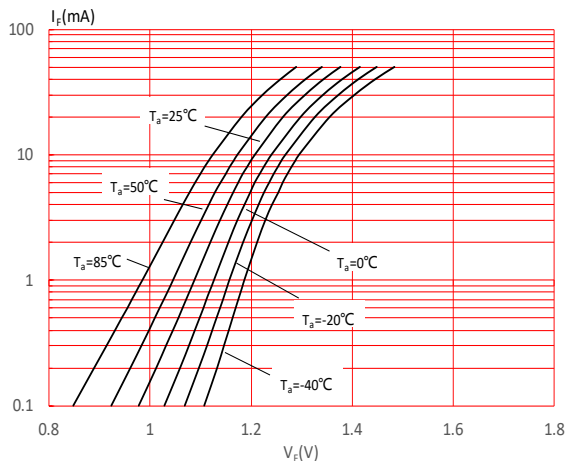


FIG.4: Forward Voltage vs. Ambient Temperature

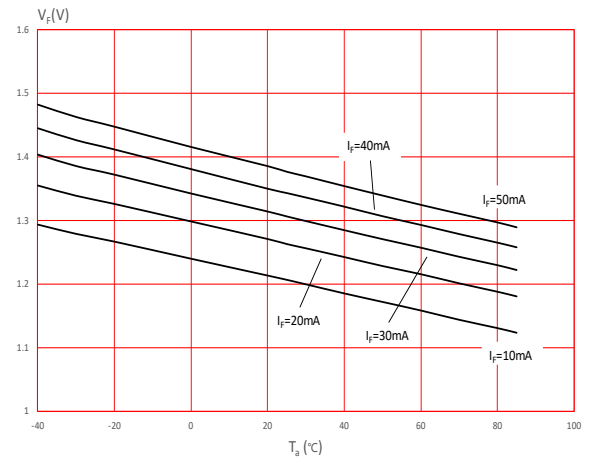


FIG.5: Off-state Terminal Current vs. Off-state Terminal Voltage

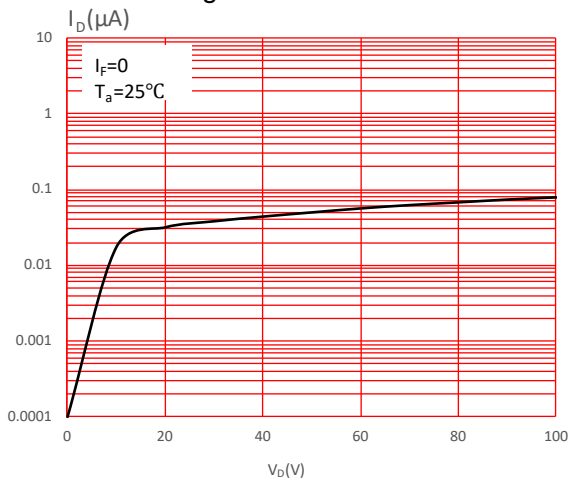
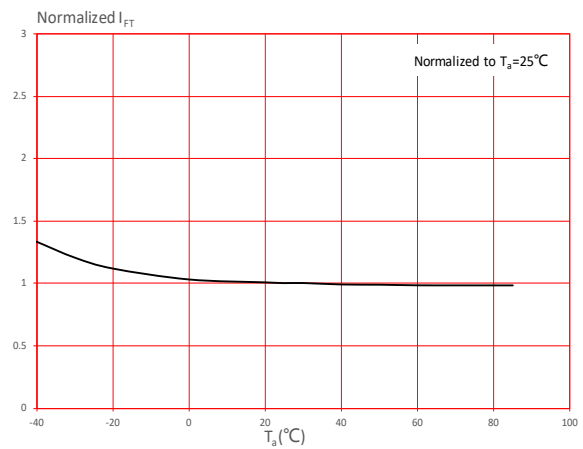
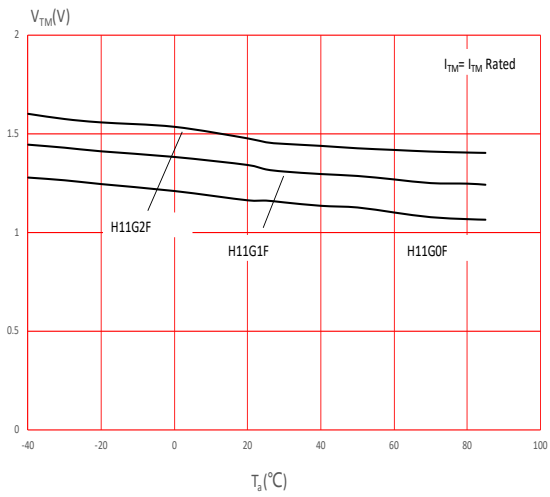


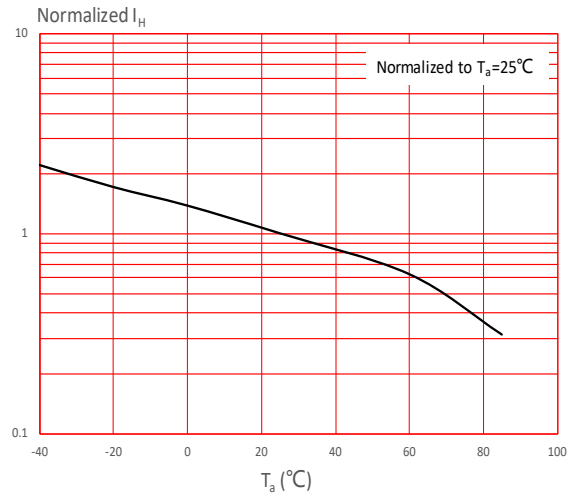
FIG.6: Normalized Trigger Current vs. Ambient Temperature



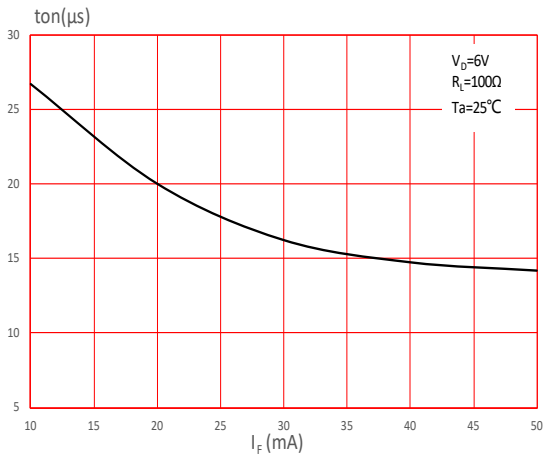
**FIG.7: On-state Terminal Voltage vs. Ambient Temperature**



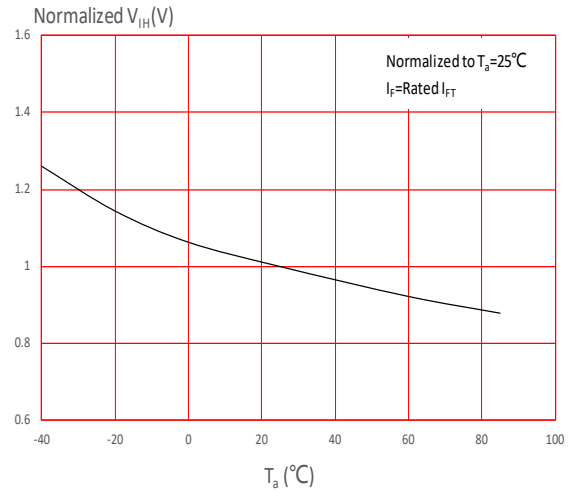
**FIG.8: Normalized Holding Current vs. Ambient Temperature**



**FIG.9: Turn On Time vs. Forward Current**

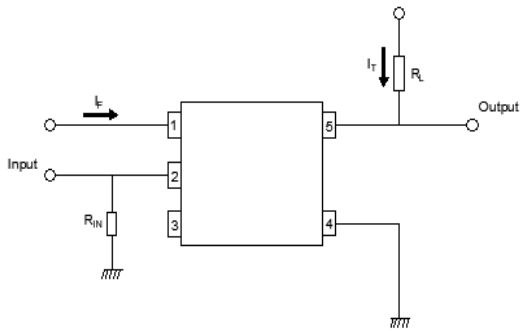


**FIG.10: Normalized Inhibit Voltage vs. Ambient Temperature**

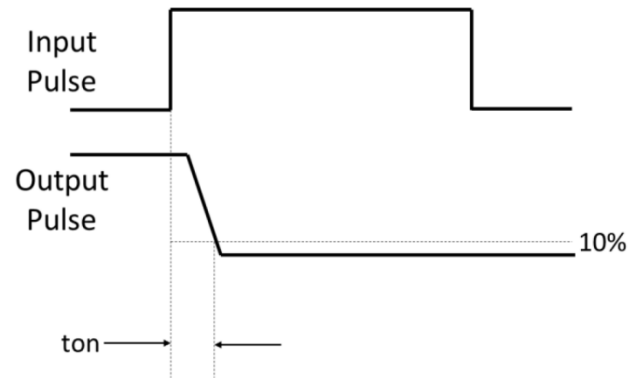


## TEST CIRCUITS

**FIG.11:** Test Circuits of Turn On Time

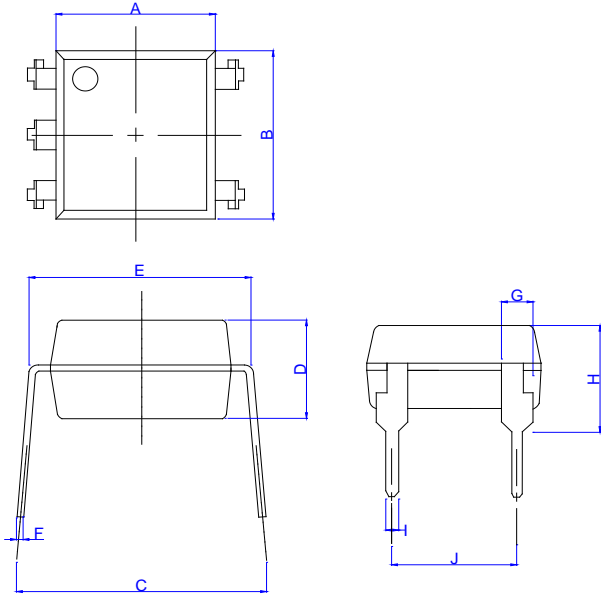


**FIG.12:** Waveforms of Turn On Time



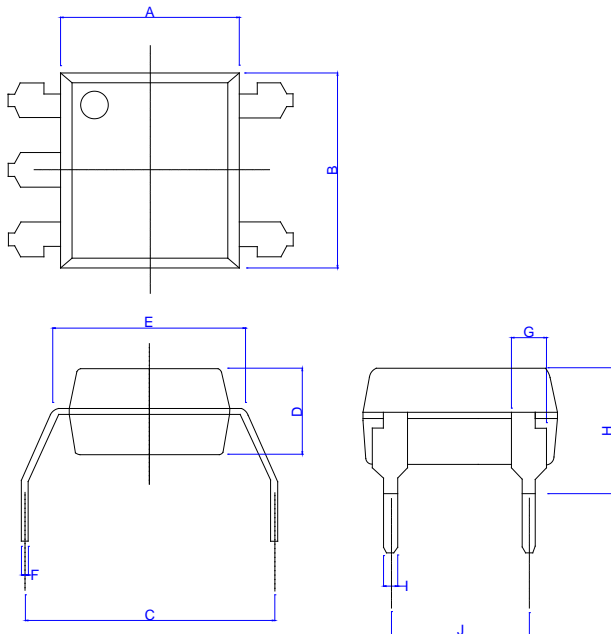
## Package Dimension (Unit: mm)

### Standard DIP Type:



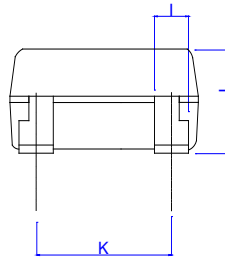
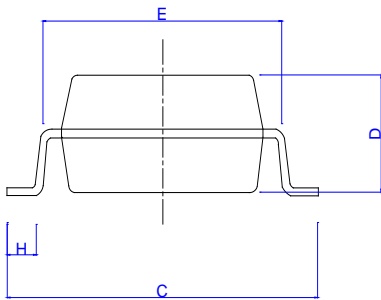
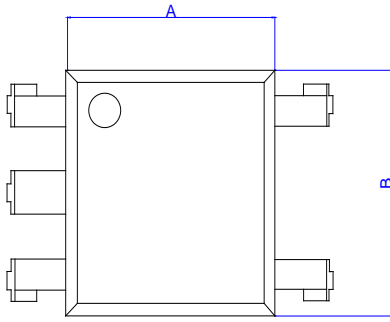
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.245		0.269
B	6.82		7.42	0.270		0.293
C	7.62		9.50	0.301		0.375
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.289		0.313
F		0.25			0.010	
G			1.30			0.051
H	4.20		4.80	0.166		0.190
I		0.50			0.020	
J		5.08			0.201	

### Option M Type:



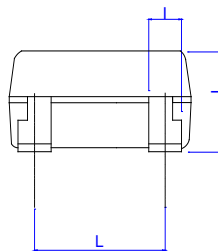
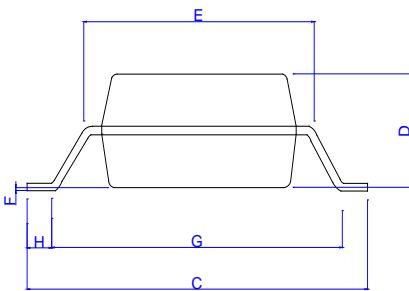
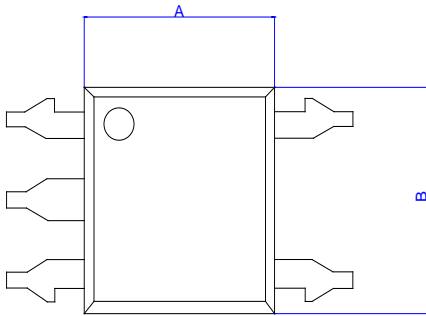
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.245		0.269
B	6.82		7.42	0.270		0.293
C	9.86		10.46	0.390		0.413
D	3.30		3.70	0.130		0.146
E	7.32		7.92	0.289		0.313
F		0.25			0.010	
G			1.30			0.051
H	4.20		4.80	0.166		0.190
I		0.50			0.020	
J		5.08			0.201	

## Option SL Type:



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.245		0.269
B	6.82		7.42	0.270		0.293
C	9.85		10.45	0.389		0.413
D	3.20		3.80	0.126		0.150
E	7.32		7.92	0.289		0.313
H	0.60			0.024		
I			1.30			0.051
J	3.35		3.95	0.132		0.156
K		5.08			0.201	

## Option SLM Type:

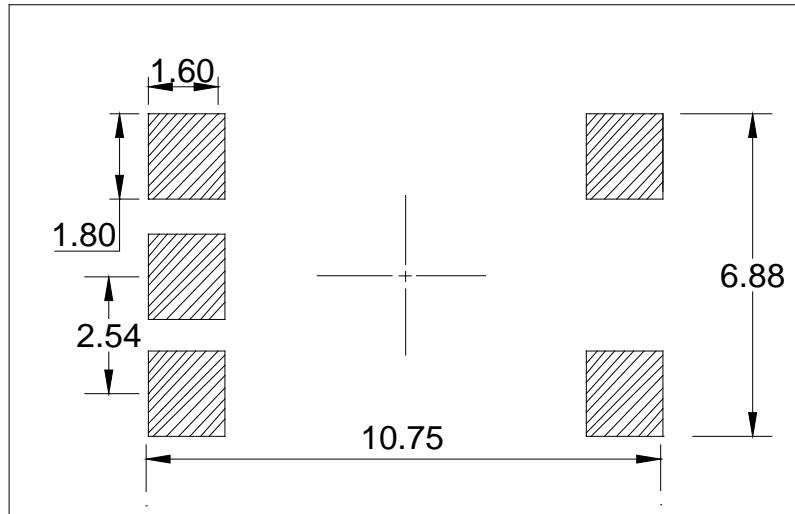


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.80	0.245		0.269
B	6.82		7.42	0.270		0.293
C	11.50		12.10	0.455		0.478
D	3.20		3.80	0.126		0.150
E	7.32		7.92	0.289		0.313
F		0.25			0.010	
G	10.20		10.80	0.403		0.427
H	0.60			0.024		
I			1.30			0.051
J	3.35		3.95	0.132		0.156
L		5.08			0.201	

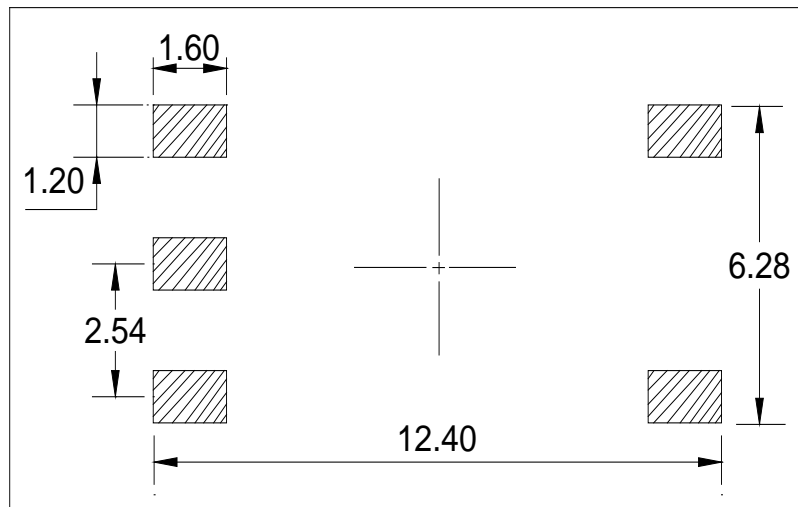


**RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)**

**Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming:**

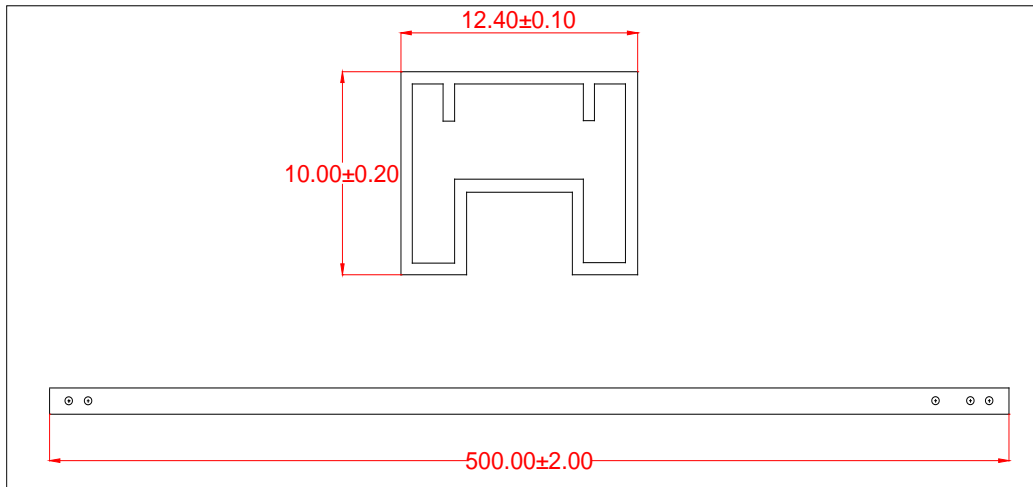


**Surface Mount (Gullwing) Lead Forming:**



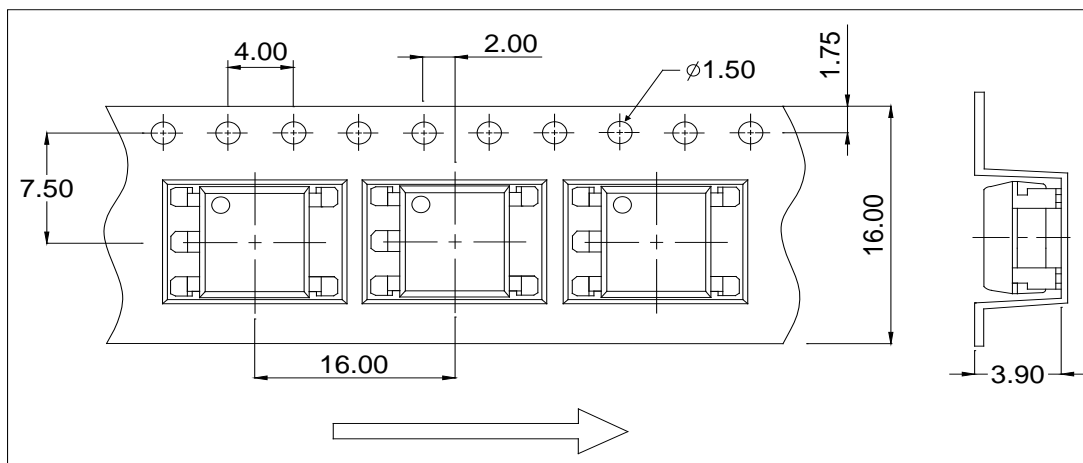
**TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

Standard DIP/M

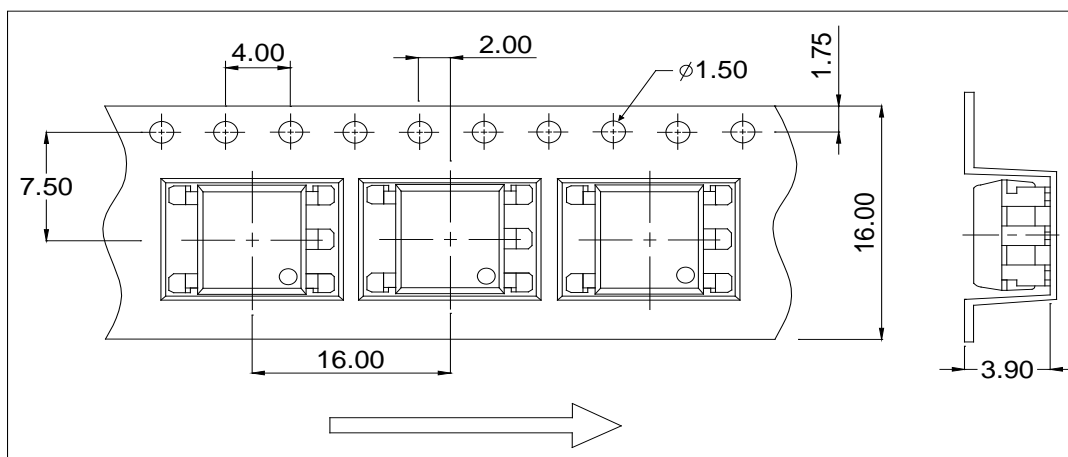


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

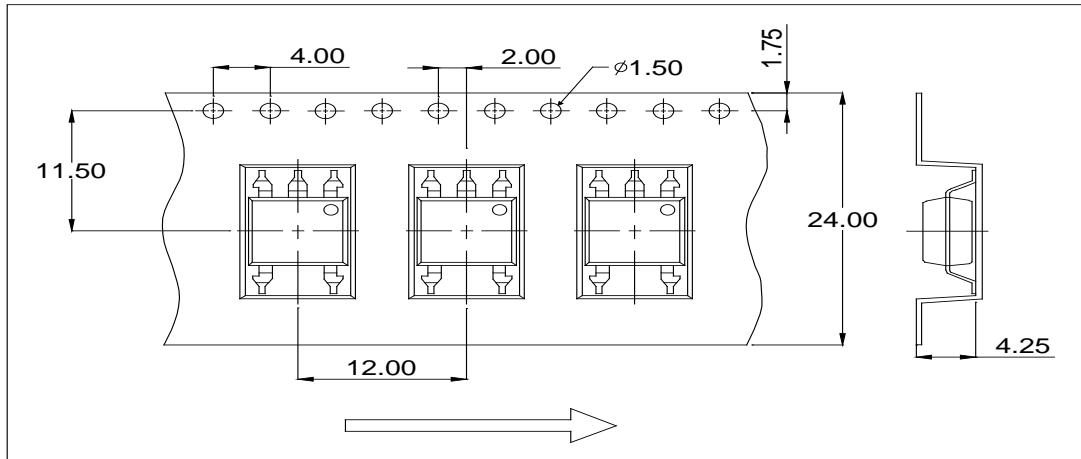
Option SL(T1)



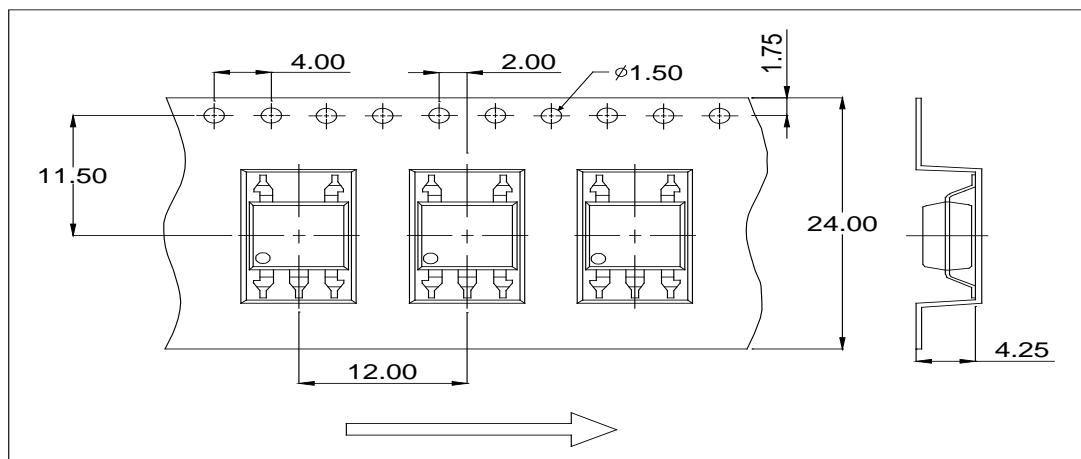
Option SL(T2)



## Option SLM(T1)

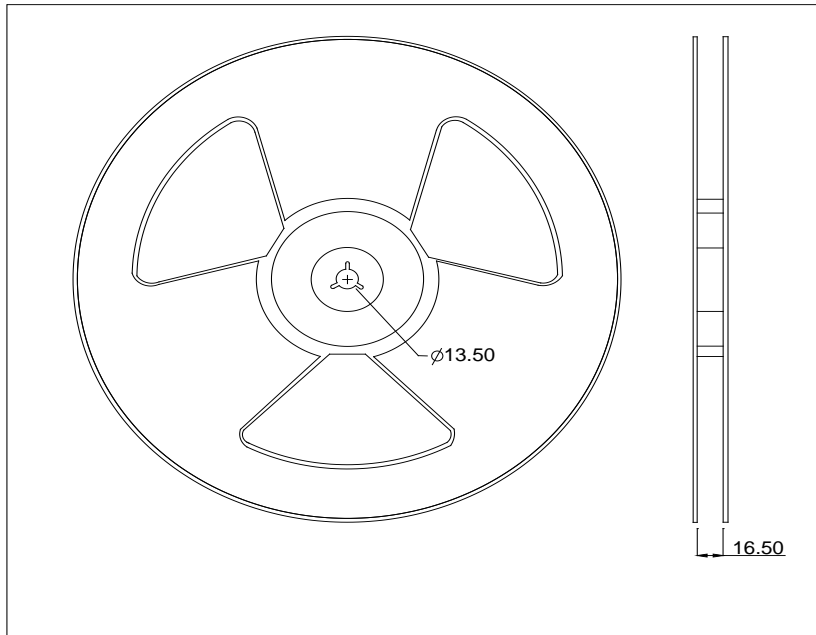


## Option SLM(T2)

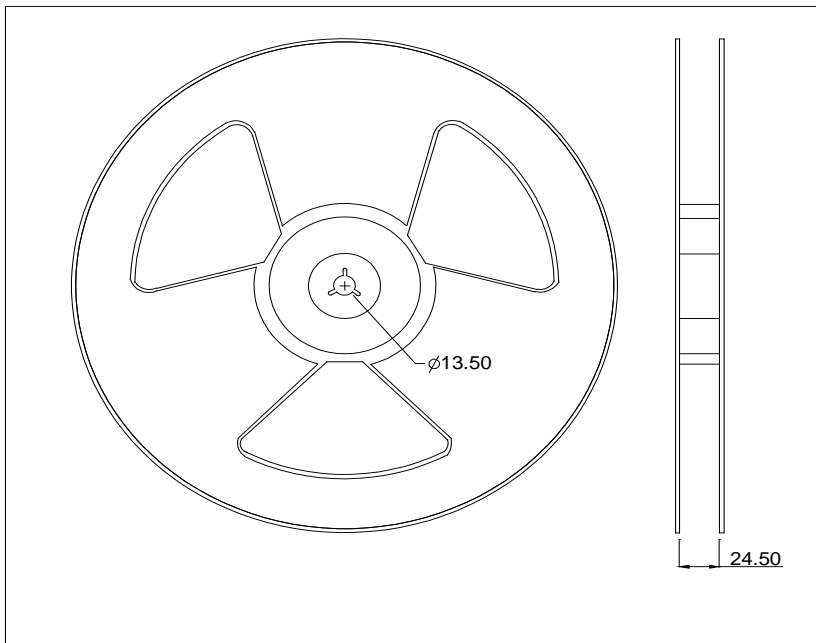


REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

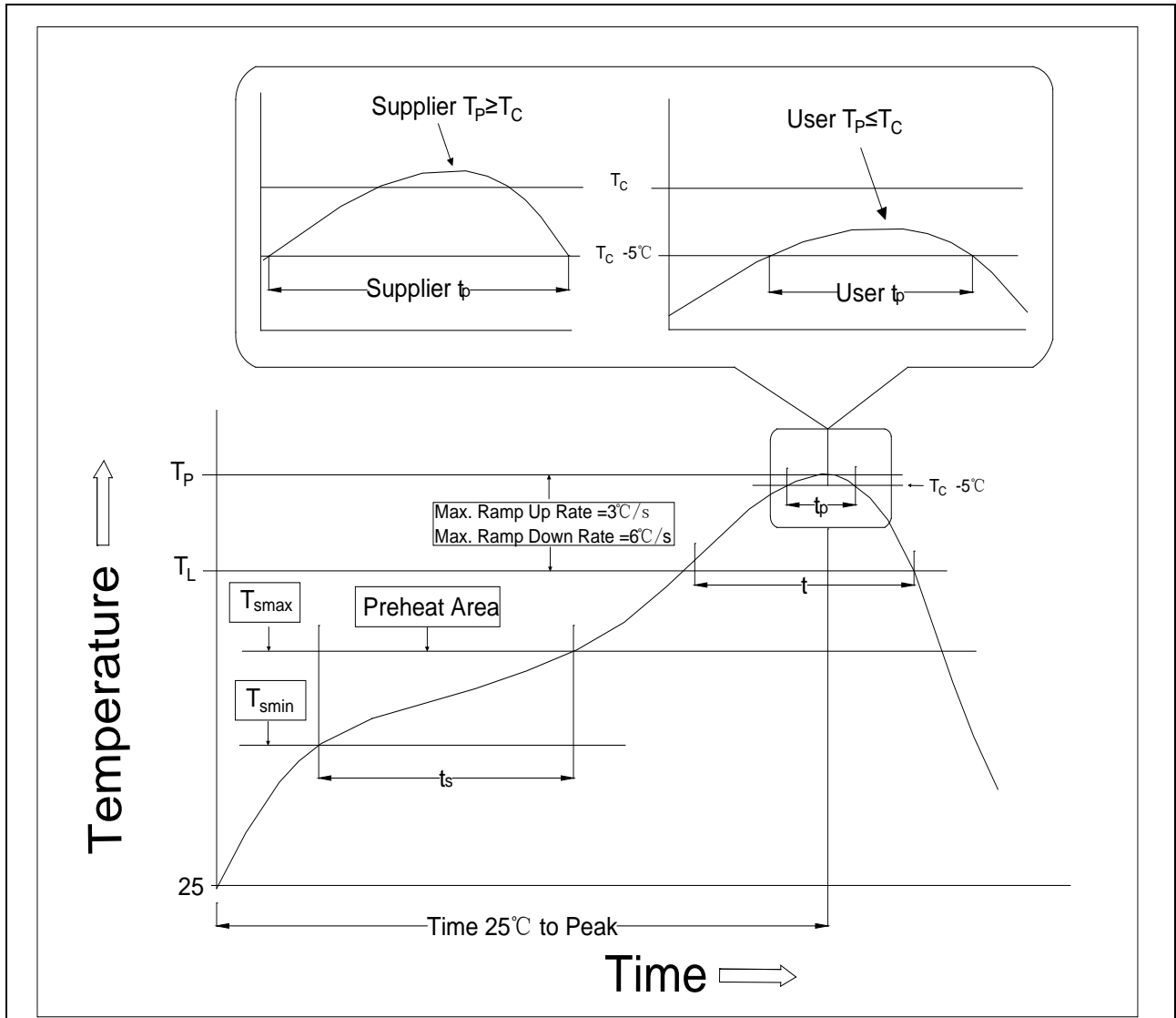
Option SL



Option SLM




REFLOW INFORMATION



Temperature Min. (T <sub>smin</sub> )	150 °C
Temperature Max. (T <sub>smax</sub> )	200 °C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3 °C/second max.
Liquidous Temperature (T <sub>L</sub> )	217 °C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-120 seconds
Peak Body Package Temperature	260 °C +0 °C / -5 °C
Time (t <sub>P</sub> ) within 5 °C of 260 °C	10 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6 °C/second max.

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